In the Claims:

- 1. (previously canceled)
- 2. (previously canceled)
- 3. (previously canceled)
- 4. (previously canceled)
- 5. (previously canceled)
- 6. (previously canceled)
- 7. (previously canceled)
- 8. (previously canceled)
- 9. (previously canceled)
- 10. (previously canceled)
- 11. (presently canceled)
- 12. (presently canceled)
- 13. (presently canceled)
- 14. (presently canceled)
- 15. (presently canceled)
- 16. (presently canceled)
- 17. (presently canceled)
- 18. (presently canceled)
- 19. (presently canceled)
- 20. (previously added) A method of making a dielectric layer between a pair of opposing electrodes comprising the steps of:

forming, as said dielectric layer, an epitaxial thin film on a textured substrate;

forming one of said electrodes on an exposed surface of said thin film;

wholly or partially removing said textured substrate; and

forming an electrical connection to access said dielectric layer on the side of said textured

substrate.

- 21. (previously added) The method according to Claim 20 wherein the textured substrate comprises nickel.
- 22. (previously added) The method according to Claim 22 wherein said epitaxial thin film is formed from perovskite.